



Seiko Seiki STP-H600, H1000

Technical Specifications

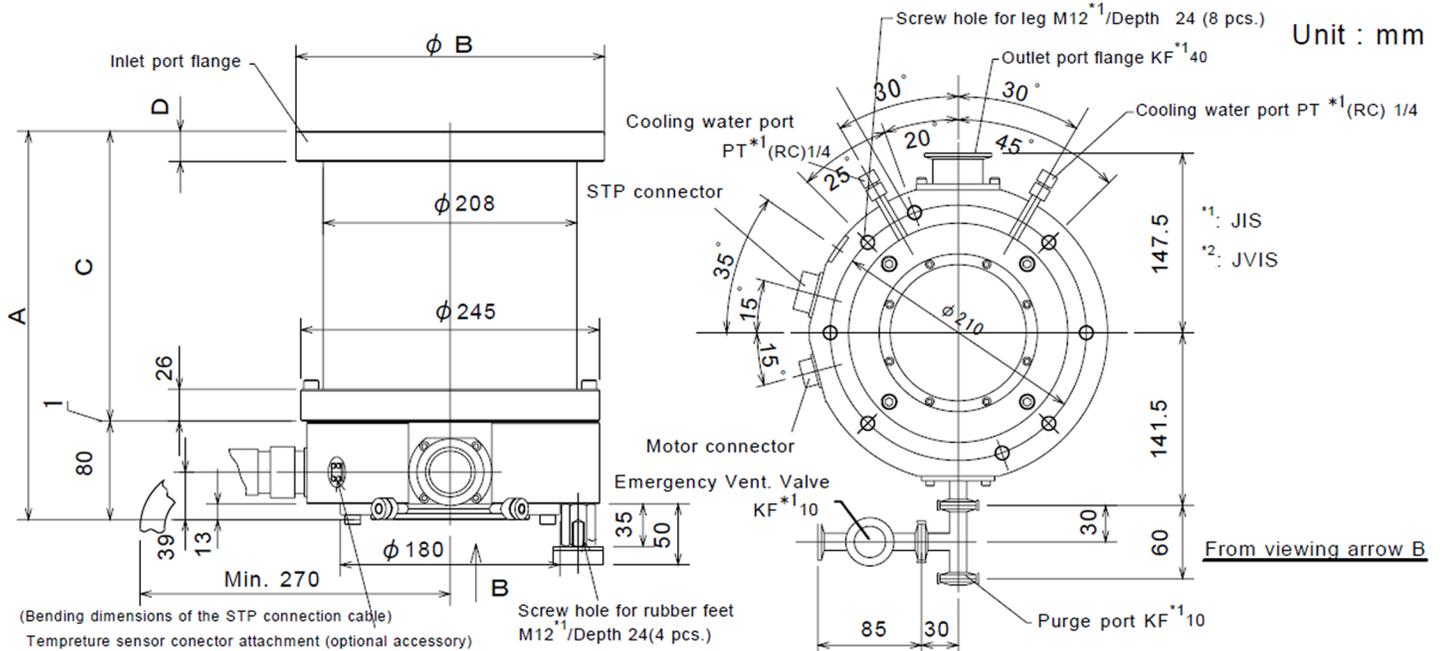
Item		STP-H600	STP-H1000
Flange size*1	Inlet port flange	ICF203/VG150/ISO160	ICF253/VG200/ISO200
	Outlet port flange	KF40	
Pumping speed	N ₂ L/s	600	1000
	He L/s	550	900
	N ₂ L/s	500	800
Compression ratio	N ₂	>10 ⁸	
	He	10 ⁴	
	N ₂	10 ³	
Ultimate pressure	Pa (Torr)	10 ⁻⁷ (10 ⁻⁹) order (after baking)	
Maximum working pressure Pa (Torr)	When cooled water:	67 (0.5)	
	When cooled air:	5.3 (0.04)	
	When cooled natural air:	0.9 (0.007)	
	When TMS unit is used:	13(0.1)	
Allowable backing pressure Pa (Torr)	When cooled water: When TMS unit is used:	400 (3)	
	When cooled air: When cooled natural air:	267 (2)	
Rated speed	rpm	35,000	
Starting time	min	6	
Stopping time	min	6	
Vibration	μ m O-P	<0.01 (at 35,000 rpm)	
Noise	dB	<50 (at 35,000 rpm)	
Baking temperature	°C	<120	
Lubricating oil		Not necessary	
Installation position		Free	
Cooling method*2		Water cooled, Air cooled, Natural air cooled	
Recommended auxiliary pump	L/min	240	
Mass*3	kg	31	32
Ambient temperature range	°C	0 to 40	
Storage temperature range	°C	- 25 to + 55	

Values shown in the above table are typical. They are not guaranteed.



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Dimensions



Dimensions List (Total Length of the Pump and Flange)

Model	STP-H600 Series				STP-H1000 Series							
	ICF ^{*2} 203	VG ^{*1} 150	ISO160	ISO160F	ICF253	VG200	ISO200	ISO200F	ISO250	ISO250F	ASA*6	
A	339	339	339	339	319	319	319	319	319	319	339	
B	$\phi 203$	$\phi 235$	$\phi 180$	$\phi 225$	$\phi 253$	$\phi 300$	$\phi 240$	$\phi 285$	$\phi 290$	$\phi 335$	$\phi 279.4$	
C	258	258	258	258	238	238	238	238	238	238	258	
D	22	14	12	16	25	18	12	16	15	16	12.4	





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PHONE: 831-462-8900

FAX: 831-462-3536

WWW.PROVAC.COM

Seiko Seiki STP-H600, H1000

Features & Benefits

- oil free
- low vibration
- high reliability
- maintenance free
- increased life
- advanced controller design
- compact design
- small footprint
- advanced rotor technology
- installation in any orientation

Applications

- plasma etch • ECR etch • film deposition • sputtering • ion implantation source • beam line pumping • MBE • diffusion • photo resist stripping
- crystal / epitaxial growth • wafer inspection • load lock chambers

Recommended backing pump

- backing pump: QDP-40